CT827 Series

DC Input 8-Pin Phototransistor Optocoupler

Features

- High isolation 5000 VRMS
- DC input with transistor output
- Operating temperature range - 55 °C to 110 °C
- External Creepage ≥ 7.5mm (S/SL Type)
- External Creepage ≥ 8.0mm (SLM Type)
- RoHS compliant
- REACH compliance
- Green material
- Regulatory Approvals
  - UL - UL1577 (E364000) (pending approval)
  - VDE - EN60747-5-5(VDE0884-5)
  - CQC – GB4943.1, GB8898
  - IEC60065, IEC60950

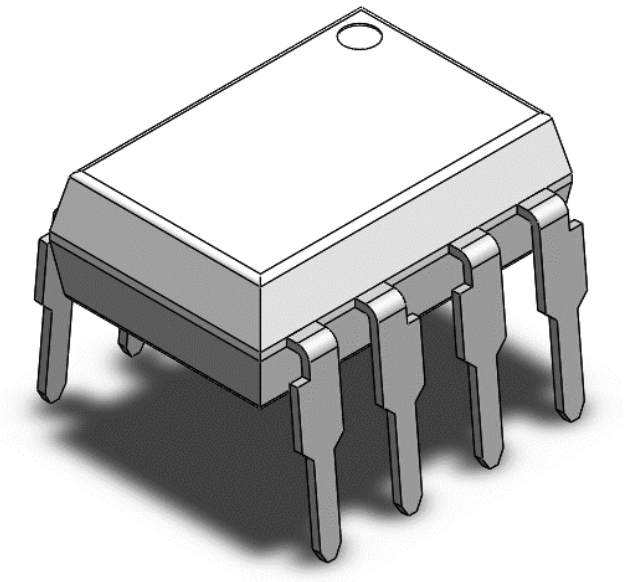
Description

The CT827 series consists of dual channels each contains a photo transistor optically coupled to a gallium arsenide Infrared-emitting diode in a 8-lead DIP package different lead forming options.

Applications

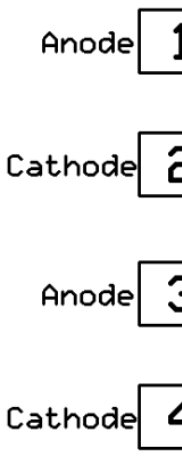
- Switch mode power supplies
- Computer peripheral interface
- Microprocessor system interface

Package Outline



Note: Different lead forming options available. See package dimension.

Schematic



Absolute Maximum Rating at 25°C

Symbol	*Parameters*	*Ratings*	*Units*	*Notes*
V_{ISO}	Isolation voltage	5000	V_{RMS}	
P_{TOT}	Total power dissipation	200	mW	
T_{OPR}	Operating temperature	-55 ~ +110	°C	
T_{STG}	Storage temperature	-55 ~ +150	°C	
T_{SOL}	Soldering temperature	260	°C	
Emitter (1 circuit)				
I_F	Forward current	60	mA	
$I_{F(TRANS)}$	Peak transient current (≤1μs P.W,300pps)	1	A	
V_R	Reverse voltage	6	V	
P_D	Emitter power dissipation	100	mW	
Detector (1 circuit)				
P_D	Detector power dissipation	150	mW	
B_{VCEO}	Collector-Emitter Breakdown Voltage	80	V	
B_{VECO}	Emitter-Collector Breakdown Voltage	7	V	
I_C	Collector Current	50	mA	

Electrical Characteristics T_A = 25°C (unless otherwise specified)

Emitter Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
V_F	Forward voltage	I_F=10mA		1.24	1.4	V	
I_R	Reverse Current	V_R = 6V	-	-	5	μA	
C_{IN}	Input Capacitance	f= 1MHz	-	10	30	pF	

Detector Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
B_{VCEO}	Collector-Emitter Breakdown	I_C= 100μA	80	-	-	V	
B_{VECO}	Emitter-Collector Breakdown	I_E= 100μA	7	-	-	V	
I_{CEO}	Collector-Emitter Dark Current	V_{CE}= 20V, I_F=0mA	-	-	100	nA	

Transfer Characteristics

Symbol	Parameters		Test Conditions	Min	Typ	Max	Units	Notes
CTR	Current Transfer Ratio	CT827	I_F= 5mA, V_{CE}= 5V	50		600	%	
		CT827A		80		160		
		CT827B		130		260		
$V_{CE(SAT)}$	Collector-Emitter Saturation Voltage		I_F= 20mA, I_C= 1mA	-	0.1	0.2	V	
R_{IO}	Isolation Resistance		V_{IO}= 500V_{DC}	$5x10^{10}$			Ω	
C_{IO}	Isolation Capacitance		f= 1MHz		0.5	1	pF	

Switching Characteristics

Symbol	Parameters	Test Conditions	Min	Typ	Max	Units	Notes
t_r	Rise Time	I_C= 2mA, V_{CE}= 2V	-	6	18	μs	
t_f	Fall Time	R_L= 100Ω	-	8	18		

Test Circuit

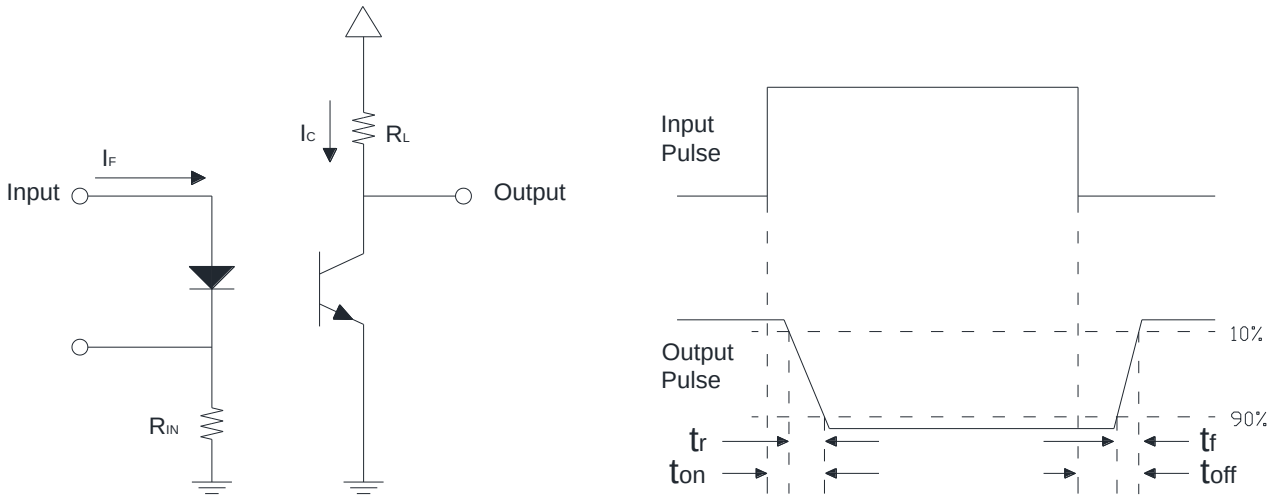
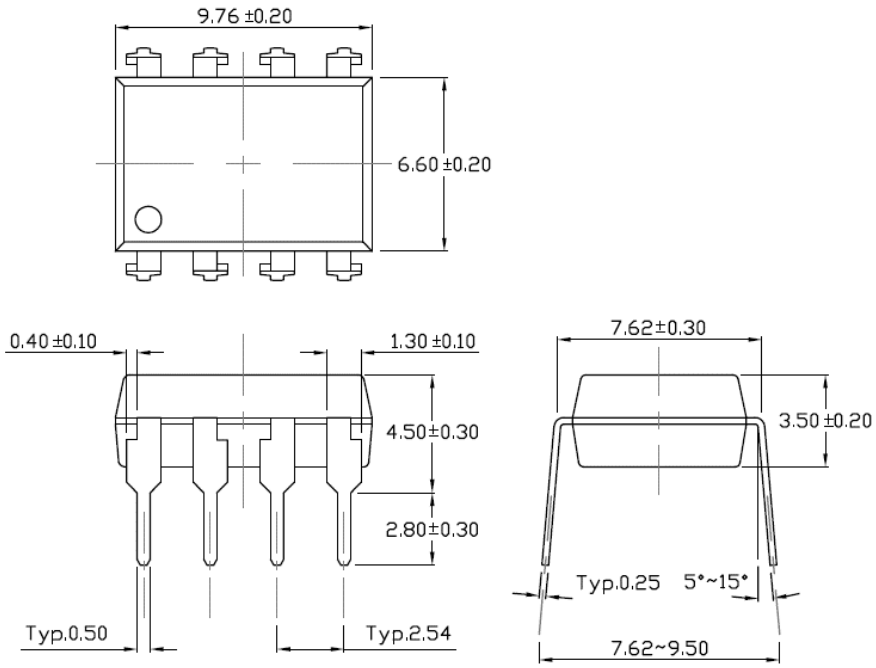


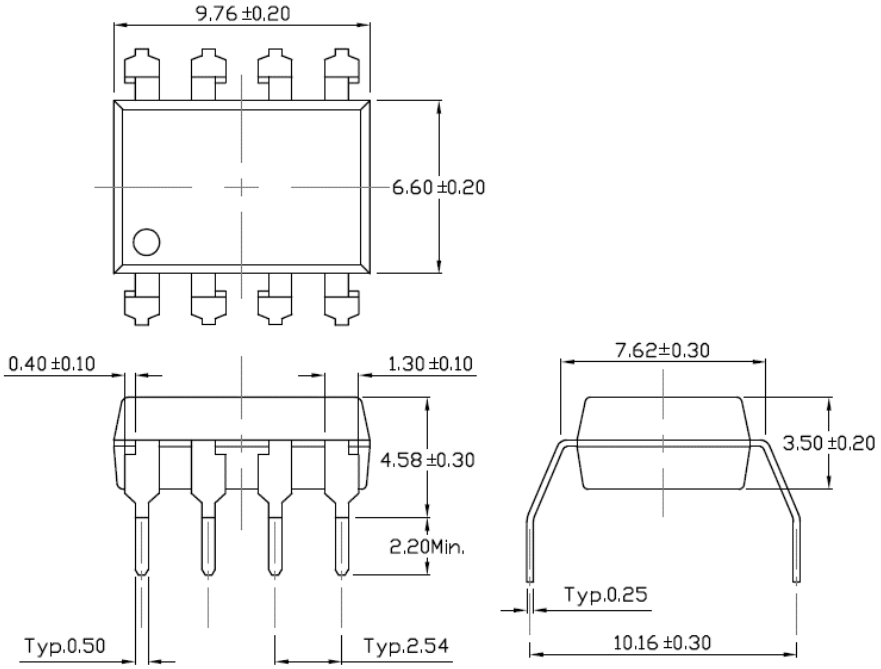
Figure 12: Switching Time Test Circuits

Package Dimension *Dimensions in mm unless otherwise stated*

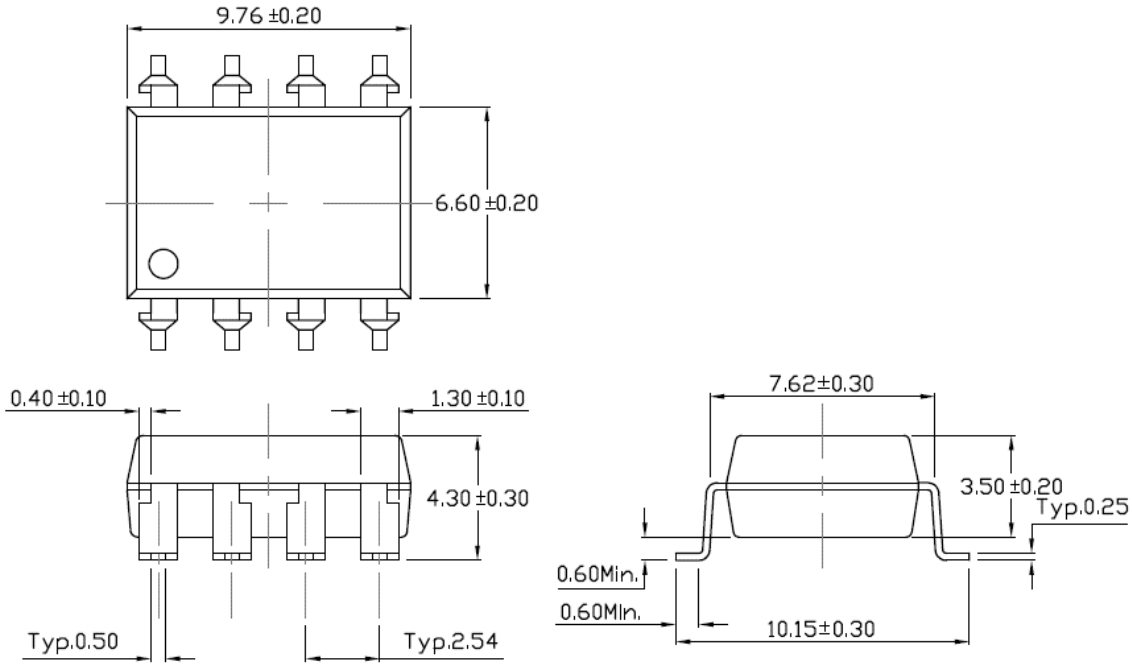
Standard DIP – Through Hole



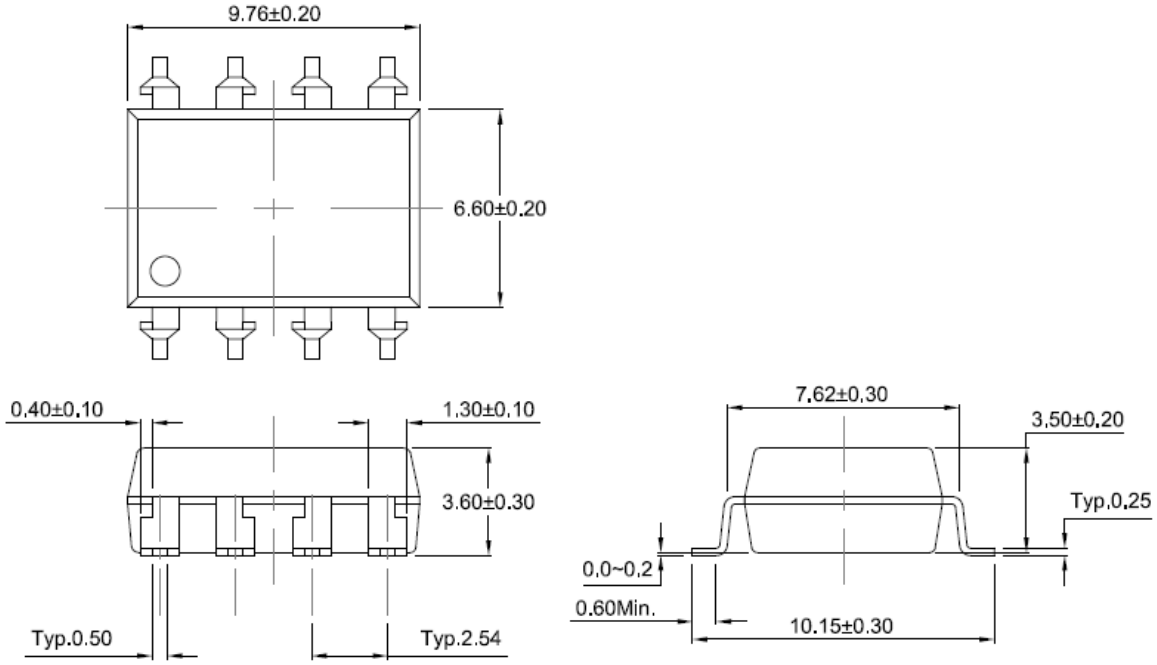
Gullwing (400mil) Lead Forming – Through Hole (M Type)



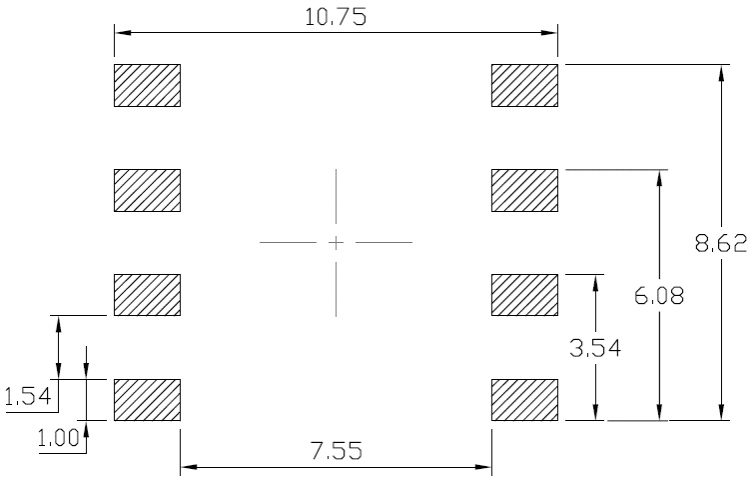
Surface Mount Lead Forming (S Type)



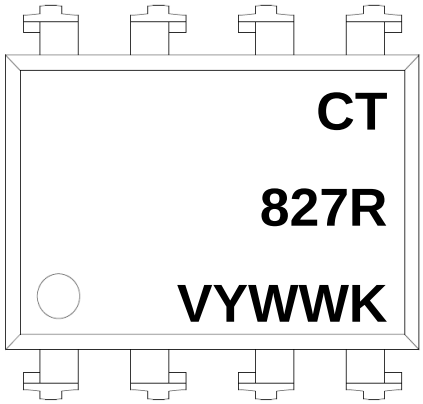
Surface Mount (Low Profile) Lead Forming (SL Type)



Recommended Solder Mask *Dimensions in mm unless otherwise stated*



Device Marking



Note:

CT	: Denotes “CT Micro”
827	: Product Number
R	: CTR Rank
V	: VDE Option
Y	: Fiscal Year
WW	: Work Week
K	: Production Code

Ordering Information

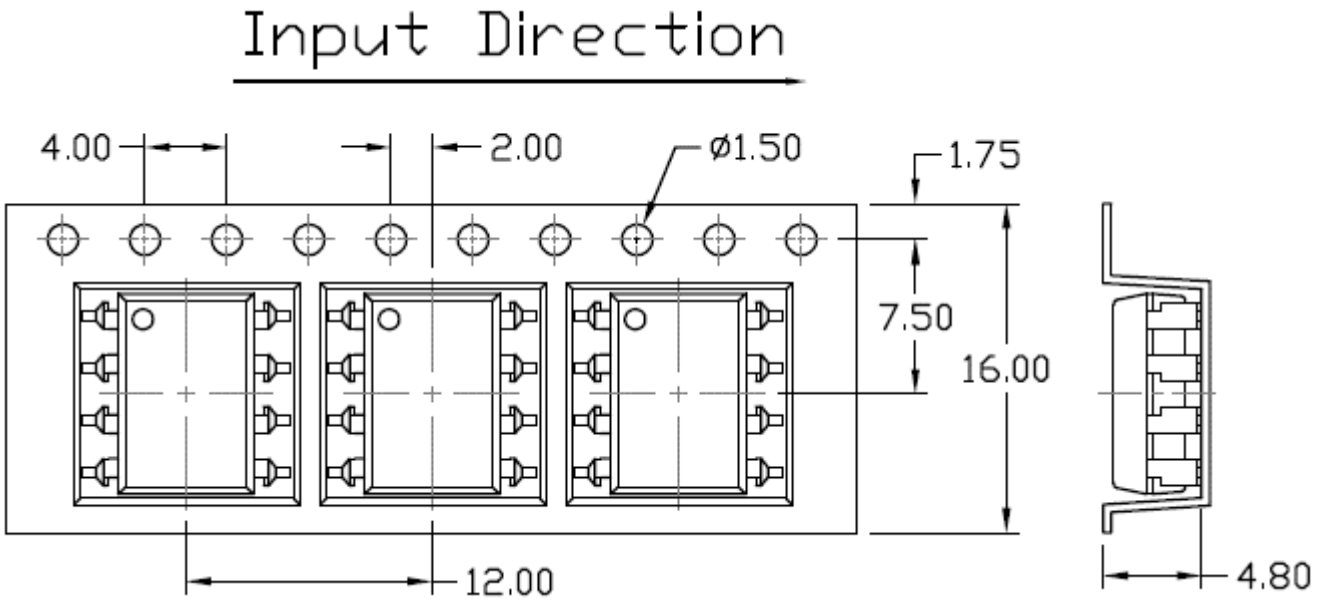
CT827X(V)(Y)(Z)

CT =Denotes “CT Micro”
827 =Product Number
X = Part No. (X=A, B or None)
V = VDE Option (V or None)
Y = Lead form option (S, SL, M or none)
Z = Tape and reel option (T1, T2 or none)

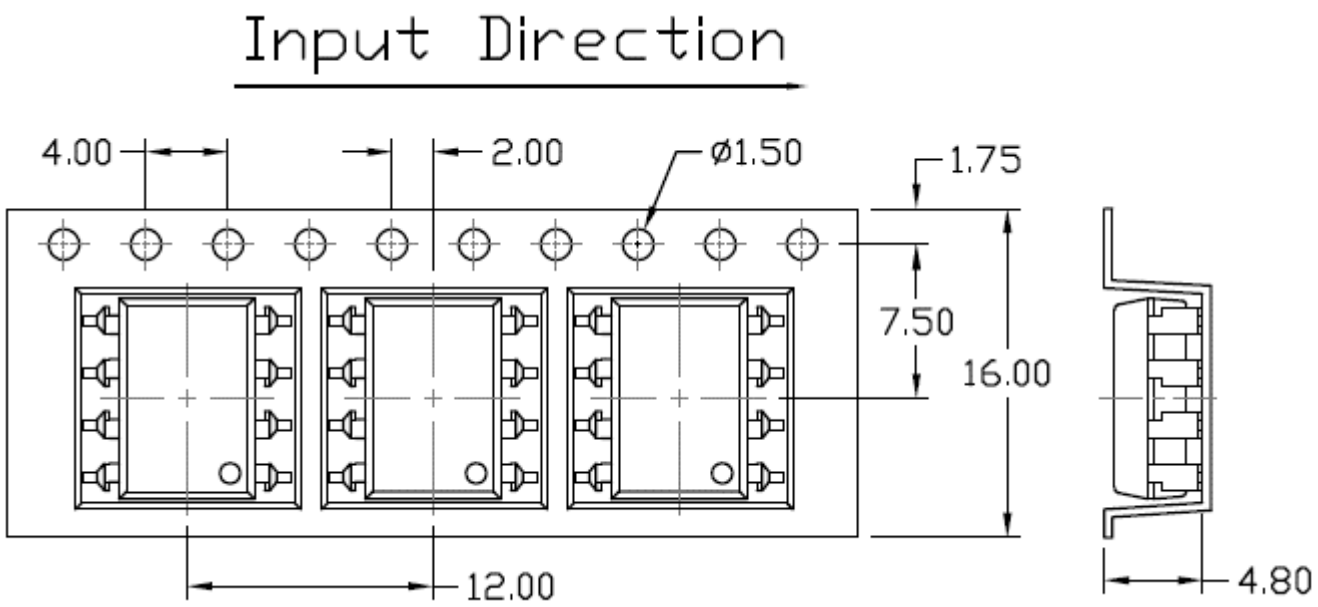
Option	***Description***	***Quantity***
None	Standard 8 Pin Dip	40 Units/Tube
M	Gullwing (400mil) Lead Forming	40 Units/Tube
S(T1)	Surface Mount Lead Forming – With Option 1 Taping	1000 Units/Reel
S(T2)	Surface Mount Lead Forming – With Option 2 Taping	1000 Units/Reel
SL(T1)	Surface Mount (Low Profile) Lead Forming– With Option 1 Taping	1000 Units/Reel
SL(T2)	Surface Mount (Low Profile) Lead Forming– With Option 2 Taping	1000 Units/Reel

Carrier Tape Specifications *Dimensions in mm unless otherwise stated*

Option S(T1) & SL(T1)

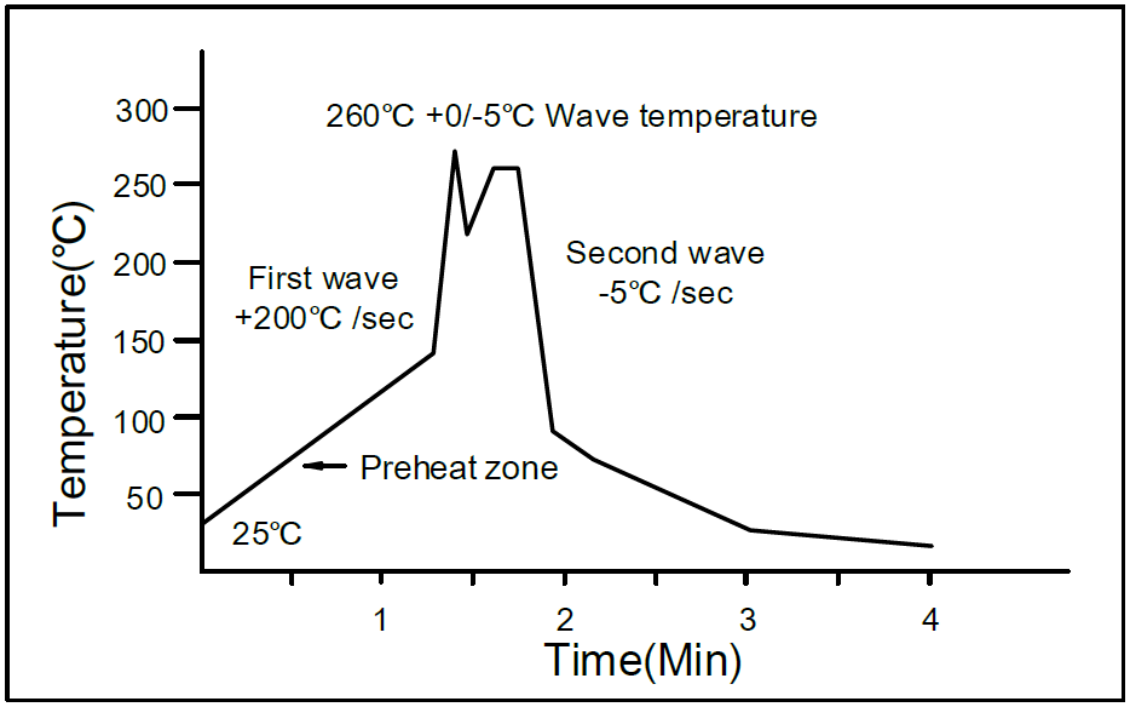


Option S(T2) & SL(T2)



Wave soldering (follow the JEDEC standard JESD22-A111)

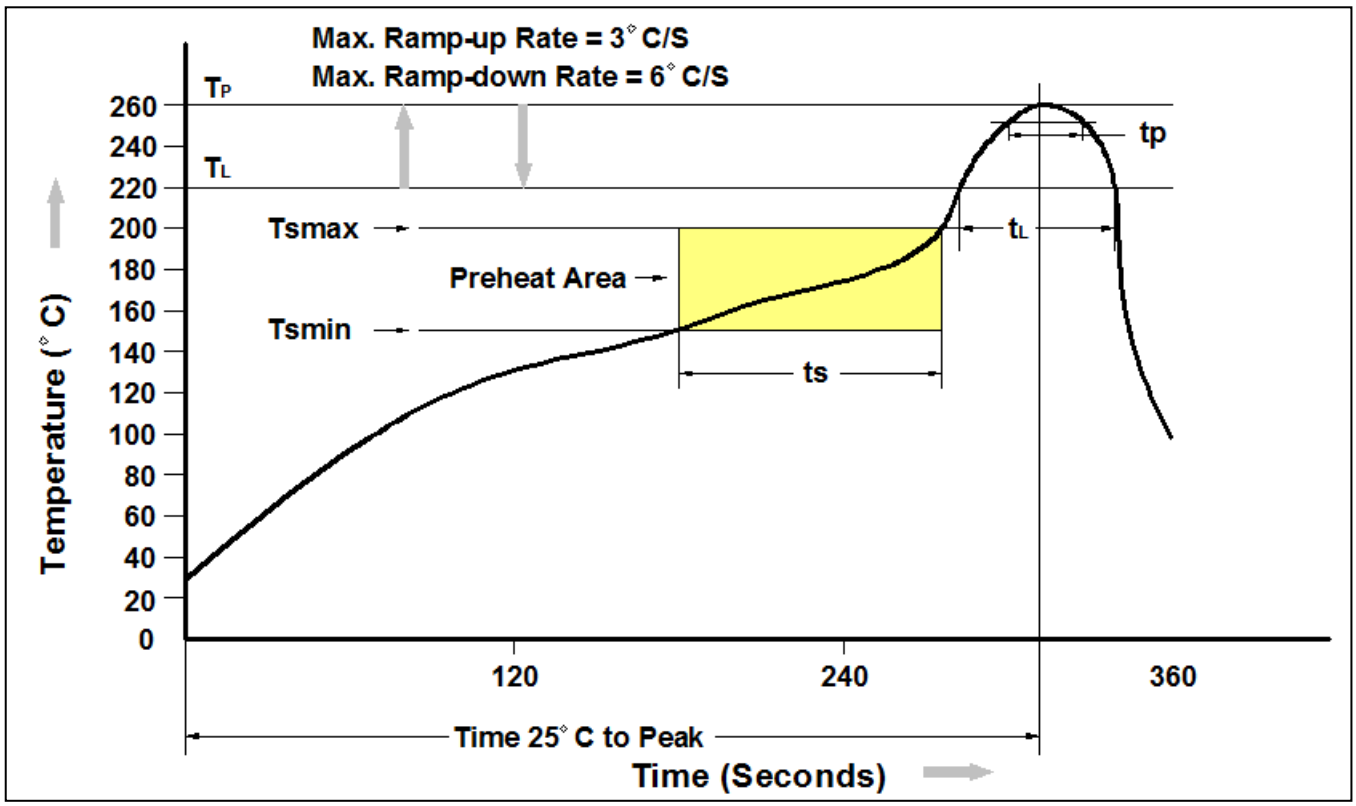
One time soldering is recommended within the condition of temperature.
Temperature: 260+0/-5˚C.
Time: 10 sec.
Preheat temperature:25 to 140˚C.
Preheat time: 30 to 80 sec.



Hand soldering by soldering iron

Allow single lead soldering in every single process.
One time soldering is recommended. Temperature: 380+0/-5˚C
Time: 3 sec max.

Reflow Profile



Profile Feature	Pb-Free Assembly Profile
Temperature Min. (Tsmin)	150°C
Temperature Max. (Tsmax)	200°C
Time (ts) from (Tsmin to Tsmax)	60-120 seconds
Ramp-up Rate (t_L to t_P)	3°C/second max.
Liquidous Temperature (T_L)	217°C
Time (t_L) Maintained Above (T_L)	60 – 150 seconds
Peak Body Package Temperature	260°C +0°C / -5°C
Time (t_P) within 5°C of 260°C	30 seconds
Ramp-down Rate (T_P to T_L)	6°C/second max
Time 25°C to Peak Temperature	8 minutes max.

DISCLAIMER

CT MICRO RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. CT MICRO DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

DISCOLORATION MIGHT OCCUR ON THE PACKAGE SURFACE AFTER SOLDERING, REFLOW OR LONG TERM USE. THIS DOES NOT IMPACT THE PRODUCT PERFORMANCE NOR THE PRODUCT RELIABILITY.

CT MICRO ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT EXPRESS WRITTEN APPROVAL OF CT MICRO INTERNATIONAL CORPORATION.

1. *Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instruction for use provided in the labelling, can be reasonably expected to result in significant injury to the user.*
2. *A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.*